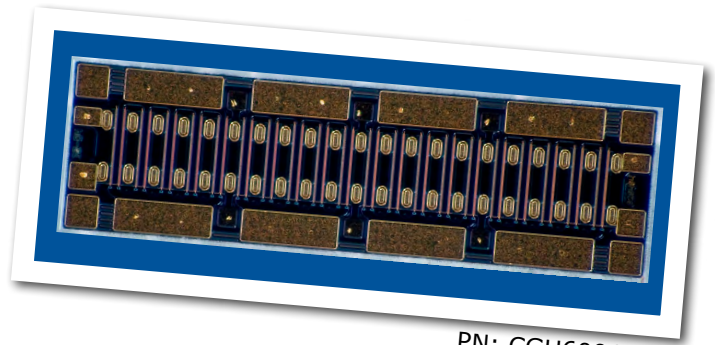


CGH60060D

60 W, 6.0 GHz, GaN HEMT Die

Cree's CGH60060D is a gallium nitride (GaN) High Electron Mobility Transistor (HEMT). GaN has superior properties compared to silicon or gallium arsenide, including higher breakdown voltage, higher saturated electron drift velocity, and higher thermal conductivity. GaN HEMTs offer greater power density and wider bandwidths compared to Si and GaAs transistors.



PN: CGH60060D

FEATURES

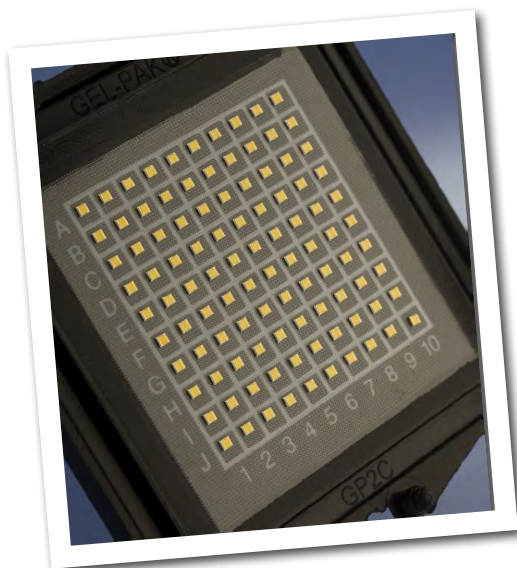
- 13 dB Typical Small Signal Gain at 4 GHz
- 12 dB Typical Small Signal Gain at 6 GHz
- 60 W Typical P_{SAT}
- 28 V Operation
- High Breakdown Voltage
- High Temperature Operation
- Up to 6 GHz Operation
- High Efficiency

APPLICATIONS

- 2-Way Private Radio
- Broadband Amplifiers
- Cellular Infrastructure
- Test Instrumentation
- Class A, AB, Linear amplifiers suitable for OFDM, W-CDMA, EDGE, CDMA waveforms



Packaging Information



- Bare die are shipped in Gel-Pak® containers.
- Non-adhesive tacky membrane immobilizes die during shipment.

Large Signal Models Available for SiC & GaN



Absolute Maximum Ratings (not simultaneous) at 25 °C

Parameter	Symbol	Rating	Units	Conditions
Drain-source Voltage	V_{DS}	84	VDC	25 °C
Gate-source Voltage	V_{GS}	-10, +2	VDC	25 °C
Storage Temperature	T_{STG}	-65, +150	°C	
Operating Junction Temperature	T_J	225	°C	
Maximum Forward Gate Current	I_{GMAX}	15	mA	25 °C
Maximum Drain Current ¹	I_{DMAX}	6	A	25 °C
Thermal Resistance, Junction to Case (packaged) ²	$R_{\theta JC}$	2.8	°C/W	
Thermal Resistance, Junction to Case (die only)	$R_{\theta JC}$	1.5	°C/W	85 °C
Mounting Temperature (30 seconds)	T_S	320	°C	30 seconds

Note¹ Current limit for long term, reliable operation

Note² Eutectic die attach using 80/20 AuSn mounted to a 60 mil thick CuMoCu carrier.

Electrical Characteristics (Frequency = 4 GHz unless otherwise stated; $T_C = 25 °C$)

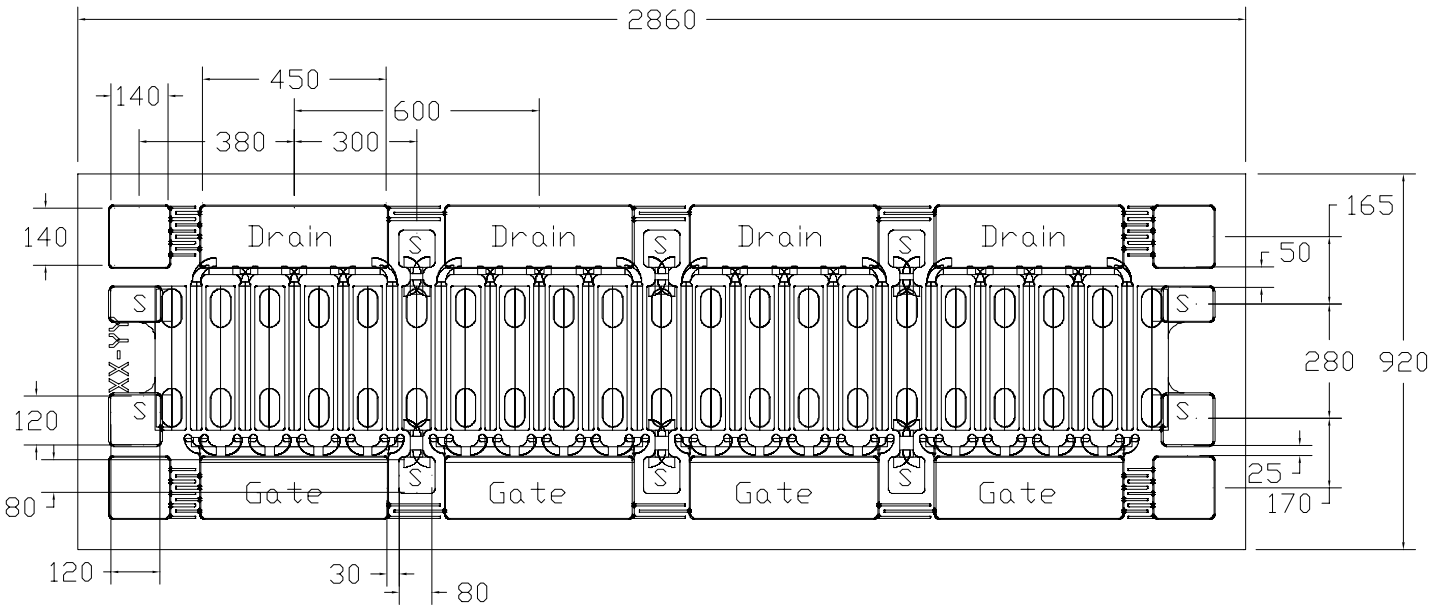
Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
DC Characteristics						
Gate Threshold Voltage	$V_{GS(TH)}$	-3.8	-3.0	-2.3	V	$V_{DS} = 10 V, I_D = 14.4 mA$
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	V _{DC}	$V_{DD} = 28 V, I_{DQ} = 400 mA$
Drain Current	I_{DS}	11.6	14.0	-	A	$V_{DS} = 6.0 V, V_{GS} = 2.0 V$
Drain-Source Breakdown Voltage	V_{BD}	120	-	-	V	$V_{GS} = -8 V, I_D = 14.4 mA$
On Resistance	R_{ON}	-	0.25	-	Ω	$V_{DS} = 0.1 V$
Gate Forward Voltage	V_{G-ON}	-	1.9	-	V	$I_{GS} = 14.4 mA$
RF Characteristics						
Small Signal Gain	G_{SS}	-	13	-	dB	$V_{DD} = 28 V, I_{DQ} = 400 mA$
Saturated Power Output ¹	P_{SAT}	-	60	-	W	$V_{DD} = 28 V, I_{DQ} = 400 mA$
Drain Efficiency ²	η	-	65	-	%	$V_{DD} = 28 V, I_{DQ} = 400 mA, P_{SAT} = 60 W$
Intermodulation Distortion ³	IM3	-	-30	-	dBc	$V_{DD} = 28 V, I_{DQ} = 400 mA,$ $P_{OUT} = 60 W PEP$
Output Mismatch Stress	VSWR	-	-	10 : 1	Ψ	No damage at all phase angles, $V_{DD} = 28 V, I_{DQ} = 400 mA,$ $P_{OUT} = 60 W CW$
Dynamic Characteristics						
Input Capacitance	C_{GS}	-	17.0	-	pF	$V_{DS} = 28 V, V_{GS} = -8 V, f = 1 MHz$
Output Capacitance	C_{DS}	-	3.5	-	pF	$V_{DS} = 28 V, V_{GS} = -8 V, f = 1 MHz$
Feedback Capacitance	C_{GD}	-	0.8	-	pF	$V_{DS} = 28 V, V_{GS} = -8 V, f = 1 MHz$

Notes:

¹ P_{SAT} is defined as $I_G = 1.4 mA$.

² Drain Efficiency = P_{OUT} / P_{DC} .

DIE Dimensions (units in microns)



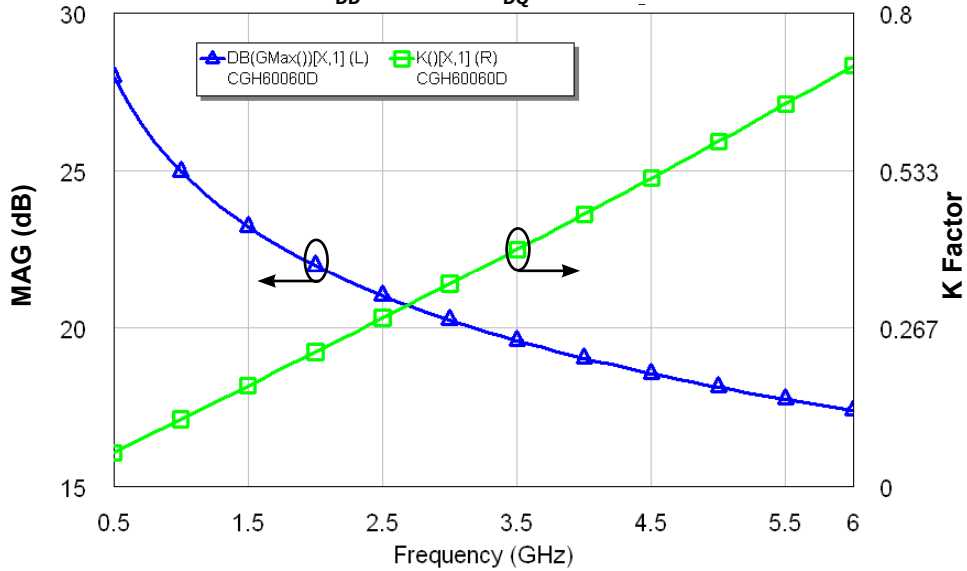
Overall die size 2860 x 920 (+0/-50) microns, die thickness 100 (+/- 10) microns.
All Gate and Drain pads must be wire bonded for electrical connection.

Assembly Notes:

- Recommended solder is AuSn (80/20) solder. Refer to Cree's website for the Eutectic Die Bond Procedure application note at http://www.cree.com/products/wireless_documents.asp
- Vacuum collet is the preferred method of pick-up.
- The backside of the die is the Source (ground) contact.
- Die back side gold plating is 5 microns thick minimum.
- Thermosonic ball or wedge bonding are the preferred connection methods.
- Gold wire must be used for connections.
- Use the die label (XX-YY) for correct orientation.

Typical Performance

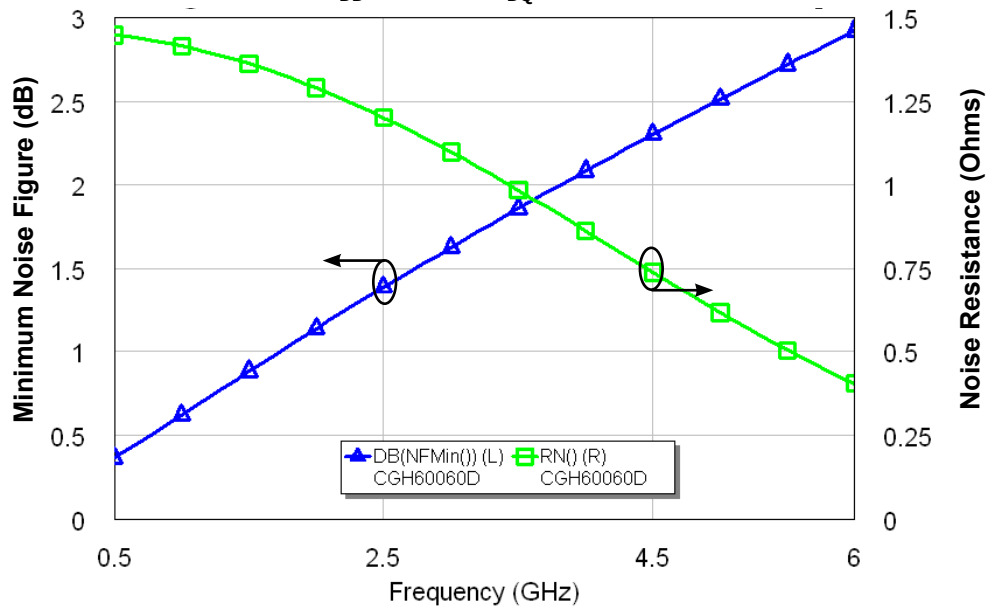
Simulated Maximum Available Gain and K Factor of the CGH60060D
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 400\text{ mA}$



Intrinsic die parameters - reference planes at centers of gate and drain bonding pads. No wire bonds assumed.

Typical Noise Performance

Simulated Minimum Noise Figure and Noise Resistance vs Frequency of the CGH60060D
 $V_{DD} = 28\text{ V}$, $I_{DQ} = 400\text{ mA}$





Typical Die S-Parameters (Small Signal, $V_{DS} = 28\text{ V}$, $I_{DQ} = 400\text{ mA}$, magnitude / angle)

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.958	-168.55	7.79	88.19	0.012	-1.00	0.654	-172.20
600 MHz	0.958	-170.42	6.48	85.81	0.012	-3.22	0.657	-172.35
700 MHz	0.958	-171.76	5.54	83.69	0.012	-5.16	0.661	-172.29
800 MHz	0.959	-172.76	4.83	81.75	0.012	-6.94	0.664	-172.13
900 MHz	0.959	-173.54	4.28	79.93	0.012	-8.59	0.668	-171.90
1.0 GHz	0.959	-174.16	3.83	78.20	0.012	-10.15	0.672	-171.63
1.1 GHz	0.960	-174.67	3.47	76.54	0.012	-11.65	0.676	-171.34
1.2 GHz	0.960	-175.09	3.16	74.94	0.012	-13.09	0.681	-171.05
1.3 GHz	0.960	-175.45	2.90	73.38	0.012	-14.48	0.686	-170.76
1.4 GHz	0.961	-175.76	2.68	71.86	0.012	-15.83	0.691	-170.47
1.5 GHz	0.961	-176.03	2.48	70.38	0.012	-17.15	0.696	-170.20
1.6 GHz	0.962	-176.27	2.31	68.93	0.012	-18.43	0.701	-169.95
1.7 GHz	0.962	-176.48	2.16	67.51	0.012	-19.68	0.706	-169.71
1.8 GHz	0.963	-176.67	2.02	66.13	0.012	-20.91	0.712	-169.49
1.9 GHz	0.963	-176.84	1.90	64.77	0.011	-22.10	0.718	-169.29
2.0 GHz	0.964	-177.00	1.79	63.43	0.011	-23.27	0.723	-169.11
2.1 GHz	0.964	-177.14	1.69	62.13	0.011	-24.41	0.729	-168.95
2.2 GHz	0.965	-177.27	1.60	60.85	0.011	-25.52	0.735	-168.81
2.3 GHz	0.965	-177.40	1.51	59.59	0.011	-26.62	0.740	-168.69
2.4 GHz	0.966	-177.51	1.44	58.36	0.011	-27.68	0.746	-168.59
2.5 GHz	0.966	-177.62	1.37	57.15	0.011	-28.73	0.752	-168.50
2.6 GHz	0.967	-177.72	1.30	55.96	0.011	-29.75	0.757	-168.43
2.7 GHz	0.967	-177.82	1.24	54.80	0.011	-30.74	0.763	-168.38
2.8 GHz	0.968	-177.92	1.18	53.66	0.010	-31.72	0.768	-168.34
2.9 GHz	0.969	-178.01	1.13	52.54	0.010	-32.67	0.774	-168.32
3.0 GHz	0.969	-178.09	1.08	51.45	0.010	-33.60	0.779	-168.31
3.2 GHz	0.970	-178.26	0.99	49.32	0.010	-35.40	0.789	-168.33
3.4 GHz	0.971	-178.41	0.91	47.27	0.010	-37.11	0.800	-168.40
3.6 GHz	0.972	-178.56	0.84	45.30	0.009	-38.75	0.809	-168.50
3.8 GHz	0.973	-178.70	0.78	43.41	0.009	-40.31	0.818	-168.63
4.0 GHz	0.974	-178.84	0.73	41.59	0.009	-41.79	0.827	-168.79
4.2 GHz	0.975	-178.97	0.67	39.85	0.009	-43.21	0.835	-168.97
4.4 GHz	0.976	-179.09	0.63	38.16	0.009	-44.56	0.843	-169.16
4.6 GHz	0.976	-179.22	0.59	36.54	0.008	-45.85	0.851	-169.37
4.8 GHz	0.977	-179.34	0.55	34.98	0.008	-47.08	0.858	-169.59
5.0 GHz	0.978	-179.46	0.52	33.48	0.008	-48.25	0.864	-169.83
5.2 GHz	0.979	-179.58	0.49	32.03	0.008	-49.37	0.870	-170.06
5.4 GHz	0.979	-179.69	0.46	30.63	0.008	-50.43	0.876	-170.30
5.6 GHz	0.980	-179.80	0.43	29.28	0.007	-51.45	0.882	-170.55
5.8 GHz	0.980	-179.91	0.41	27.97	0.007	-52.42	0.887	-170.79
6.0 GHz	0.981	-179.98	0.39	26.71	0.007	-53.35	0.892	-171.04

Contact Cree to receive this s-parameter file in ".s2p" format at Wireless_Sales@cree.com



Typical Die S-Parameters (Small Signal, $V_{DS} = 28\text{ V}$, $I_{DQ} = 800\text{ mA}$, magnitude / angle)

Frequency	Mag S11	Ang S11	Mag S21	Ang S21	Mag S12	Ang S12	Mag S22	Ang S22
500 MHz	0.966	-169.62	7.61	88.58	0.010	-0.60	0.693	-174.43
600 MHz	0.966	-171.35	6.34	86.43	0.010	-2.57	0.696	-174.53
700 MHz	0.966	-172.58	5.42	84.54	0.010	-4.29	0.698	-174.48
800 MHz	0.966	-173.51	4.73	82.80	0.010	-5.85	0.700	-174.35
900 MHz	0.967	-174.23	4.20	81.17	0.010	-7.31	0.703	-174.16
1.0 GHz	0.967	-174.81	3.76	79.62	0.010	-8.68	0.706	-173.95
1.1 GHz	0.967	-175.29	3.41	78.13	0.010	-10.00	0.709	-173.72
1.2 GHz	0.967	-175.69	3.11	76.69	0.010	-11.27	0.712	-173.47
1.3 GHz	0.967	-176.03	2.86	75.28	0.009	-12.51	0.715	-173.23
1.4 GHz	0.968	-176.32	2.64	73.91	0.009	-13.70	0.718	-172.99
1.5 GHz	0.968	-176.58	2.45	72.57	0.009	-14.87	0.722	-172.75
1.6 GHz	0.968	-176.80	2.29	71.26	0.009	-16.01	0.726	-172.52
1.7 GHz	0.969	-177.00	2.14	69.97	0.009	-17.13	0.729	-172.30
1.8 GHz	0.969	-177.18	2.01	68.71	0.009	-18.22	0.733	-172.09
1.9 GHz	0.969	-177.35	1.89	67.46	0.009	-19.30	0.737	-171.90
2.0 GHz	0.970	-177.49	1.78	66.24	0.009	-20.35	0.741	-171.72
2.1 GHz	0.970	-177.63	1.69	65.04	0.009	-21.38	0.746	-171.55
2.2 GHz	0.970	-177.76	1.60	63.85	0.009	-22.39	0.750	-171.39
2.3 GHz	0.971	-177.88	1.52	62.69	0.009	-23.38	0.754	-171.25
2.4 GHz	0.971	-177.99	1.44	61.55	0.009	-24.35	0.758	-171.12
2.5 GHz	0.971	-178.09	1.37	60.42	0.009	-25.31	0.763	-171.00
2.6 GHz	0.972	-178.19	1.31	59.31	0.009	-26.25	0.767	-170.90
2.7 GHz	0.972	-178.28	1.25	58.22	0.009	-27.16	0.771	-170.81
2.8 GHz	0.972	-178.37	1.20	57.15	0.008	-28.07	0.776	-170.73
2.9 GHz	0.973	-178.45	1.15	56.09	0.008	-28.95	0.780	-170.66
3.0 GHz	0.973	-178.54	1.10	55.05	0.008	-29.82	0.784	-170.60
3.2 GHz	0.974	-178.69	1.01	53.02	0.008	-31.50	0.793	-170.52
3.4 GHz	0.974	-178.83	0.93	51.06	0.008	-33.12	0.801	-170.48
3.6 GHz	0.975	-178.97	0.87	49.17	0.008	-34.67	0.809	-170.48
3.8 GHz	0.976	-179.10	0.80	47.33	0.008	-36.16	0.817	-170.51
4.0 GHz	0.977	-179.22	0.75	45.56	0.007	-37.59	0.824	-170.56
4.2 GHz	0.977	-179.35	0.70	43.84	0.007	-38.96	0.831	-170.64
4.4 GHz	0.978	-179.46	0.66	42.18	0.007	-40.27	0.838	-170.74
4.6 GHz	0.978	-179.58	0.61	40.57	0.007	-41.53	0.845	-170.86
4.8 GHz	0.979	-179.69	0.58	39.02	0.007	-42.74	0.852	-170.99
5.0 GHz	0.980	-179.80	0.54	37.51	0.007	-43.90	0.858	-171.13
5.2 GHz	0.980	-179.90	0.51	36.06	0.007	-45.01	0.863	-171.29
5.4 GHz	0.981	179.99	0.48	34.65	0.006	-46.07	0.869	-171.46
5.6 GHz	0.981	179.89	0.46	33.28	0.006	-47.09	0.874	-171.63
5.8 GHz	0.982	179.79	0.43	31.96	0.006	-48.06	0.879	-171.81
6.0 GHz	0.982	179.69	0.41	30.67	0.006	-49.00	0.884	-171.99

Contact Cree to receive this s-parameter file in ".s2p" format at Wireless_Sales@cree.com



Disclaimer

Specifications are subject to change without notice. Cree, Inc. believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Cree for its use or for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Cree. Cree makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Cree in large quantities and are provided for information purposes only. These values can and do vary in different applications, and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Cree products are not designed, intended, or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Cree product could result in personal injury or death, or in applications for the planning, construction, maintenance or direct operation of a nuclear facility. CREE and the CREE logo are registered trademarks of Cree, Inc.

For more information, please contact:

Cree, Inc.
4600 Silicon Drive
Durham, North Carolina, USA 27703
www.cree.com/wireless

Sarah Miller
Marketing & Export
Cree, RF Components
1.919.407.5302

Ryan Baker
Marketing
Cree, RF Components
1.919.407.7816

Tom Dekker
Sales Director
Cree, RF Components
1.919.407.5639

Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



Телефон: 8 (812) 309-75-97 (многоканальный)

Факс: 8 (812) 320-03-32

Электронная почта: ocean@oceanchips.ru

Web: <http://oceanchips.ru/>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А